

# Specification of Thermoelectric Module

## TEFC1-02312L1

### Description

The 23 couples, 6mm × 8mm size module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 74 °C, designed for superior cooling and heating up to 100/200 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

### Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

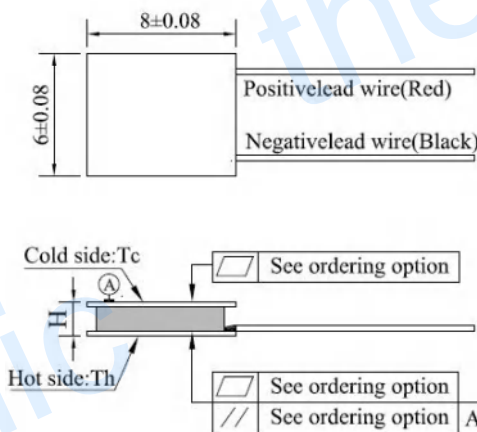
### Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

### Performance Specification Sheet

|                            |      |      |   |
|----------------------------|------|------|---|
| Th (°C)                    | 27   | 50   | Hot side temperature at environment: dry air, N <sub>2</sub>  |
| DT <sub>max</sub> (°C)     | 74   | 83   | Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side |
| U <sub>max</sub> (Voltage) | 3.03 | 3.26 | Voltage applied to the module at DT <sub>max</sub>  |
| I <sub>max</sub> (Amps)    | 1.2  | 1.2  | DC current through the modules at DT <sub>max</sub>   |
| Q <sub>Cmax</sub> (Watts)  | 2.32 | 2.53 | Cooling capacity at cold side of the module under DT=0 °C   |
| AC resistance (Ohms)       | 2.0  | 2.1  | The module resistance is tested under AC  |
| Tolerance (%)              | 10%  |      | For thermal and electricity parameters  |

### Geometric Characteristics Dimensions in millimeters



### Manufacturing Options

#### A. Solder:

1. T100: BiSn (T<sub>melt</sub>=138°C)
2. T200: CuAgSn (T<sub>melt</sub> = 217°C)
3. T240: SbSn (T<sub>melt</sub> = 240°C)

#### B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant

#### C. Ceramics:

1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)
2. Aluminum Nitride (AlN)

#### D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized

### Ordering Option

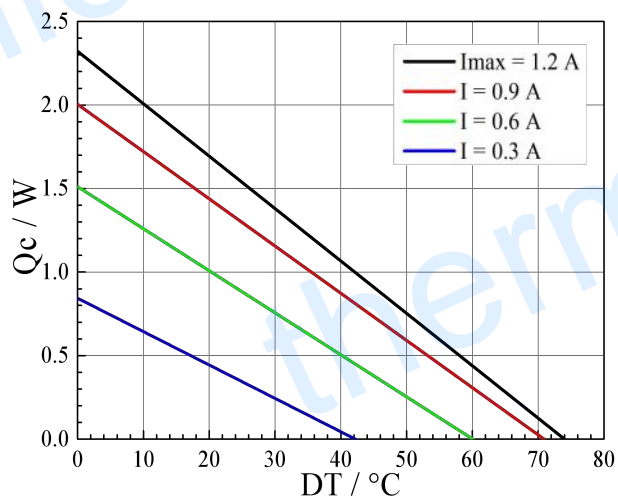
| Suffix | Thickness<br>H (mm) | Flatness/ Parallelism (mm) | Lead wire length(mm)<br>Standard/Optional length |
|--------|---------------------|----------------------------|--|
| TF     | 0:2.5 ± 0.1         | 0: 0.03/0.03               | 20±3/Specify                                     |
| TF     | 1:2.5 ± 0.03        | 1: 0.015/0.015             | 20±3/Specify                                     |

Eg. TF01: Thickness 2.5 ± 0.1 (mm) and Flatness 0.015/0.015 (mm)

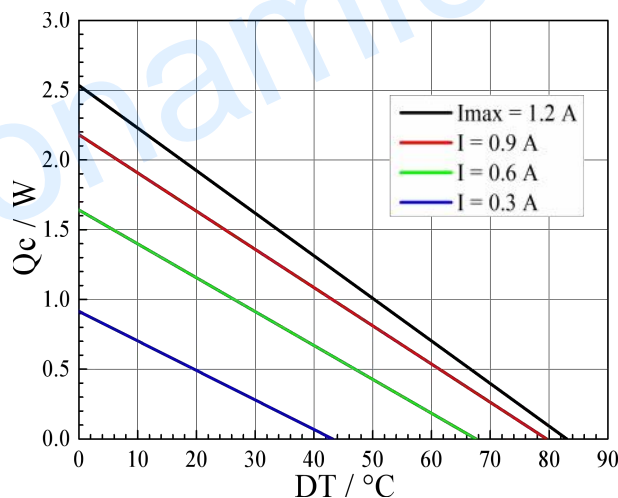
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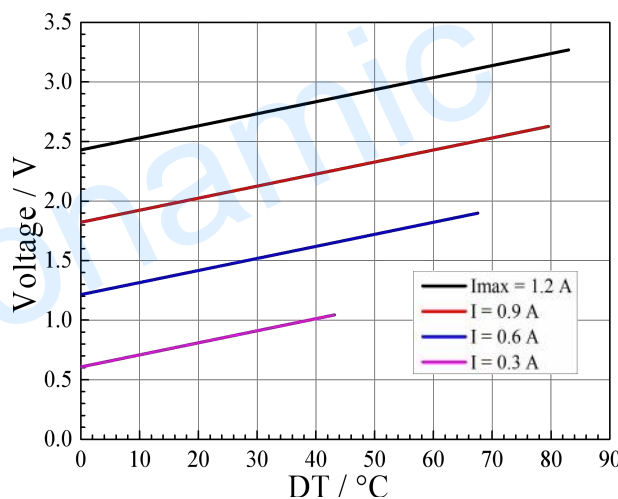
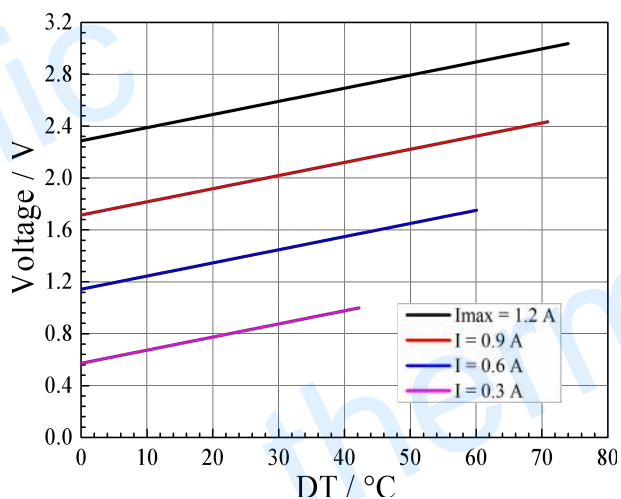
### Performance Curves at Th=27 °C



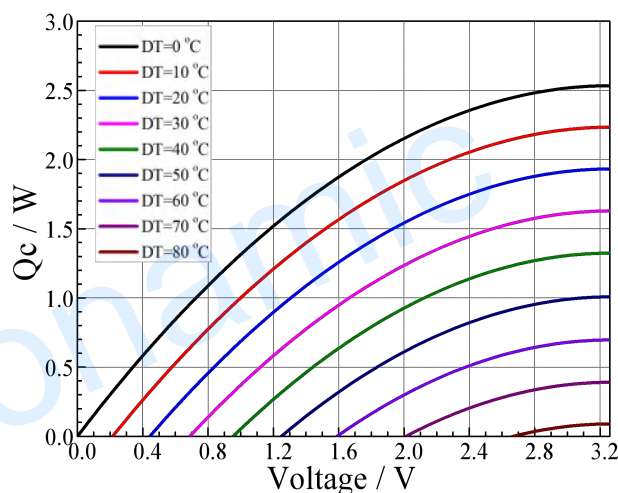
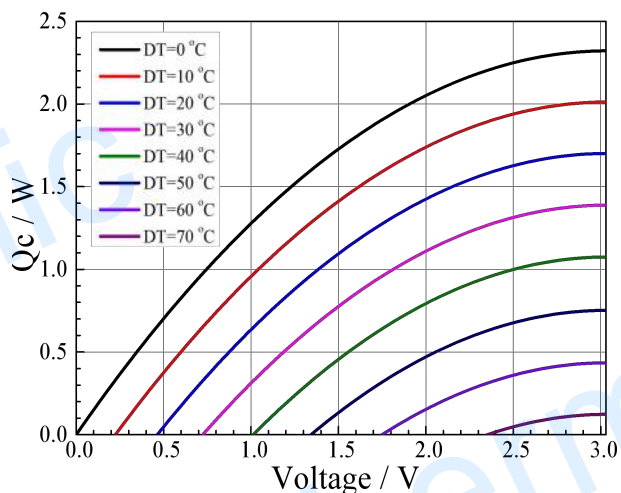
### Performance Curves at Th=50 °C



Standard Performance Graph  $Q_c = f(DT)$



Standard Performance Graph  $V = f(DT)$

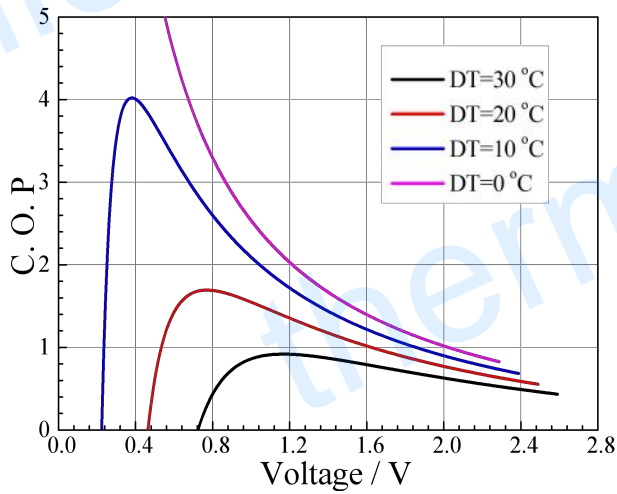


Standard Performance Graph  $Q_c = f(V)$

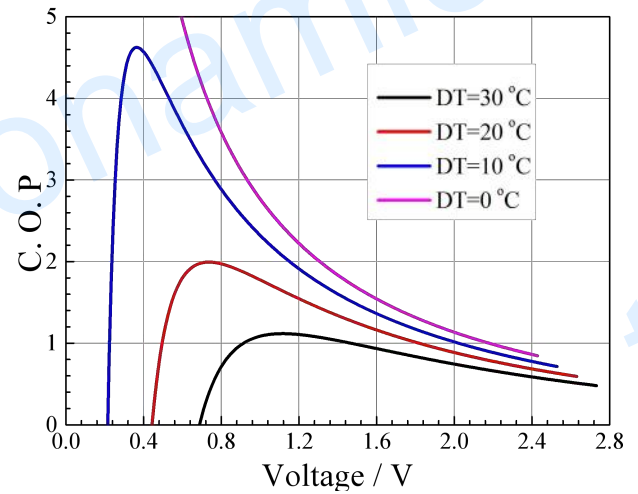
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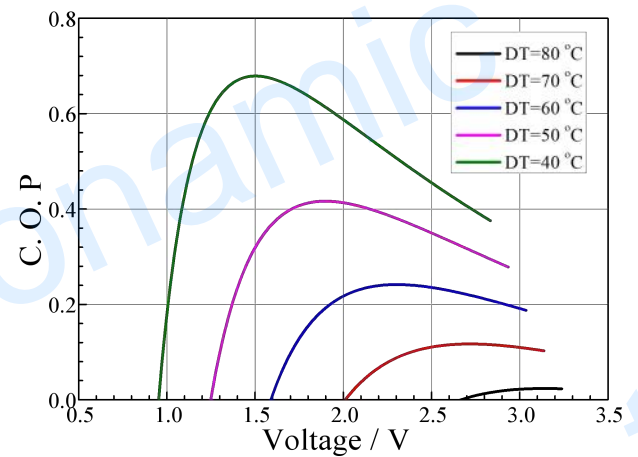
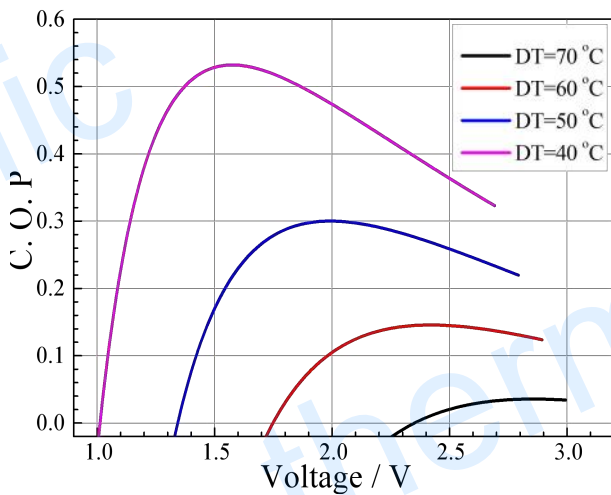
### Performance Curves at Th=27 °C



### Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of DT ranged from 40 to 70/80 °C

**Remark:** The coefficient of performance (COP) is the cooling power  $Q_c$ /Input power ( $V \times I$ ).

### Operation Caution

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below  $I_{max}$  or  $V_{max}$
- Work under DC

**Note:** All specifications subject to change without notice.